

## Minutes from OpenPICs WP 4 meeting 10-04-2017

Present: Longfei, Steven, Rob, Tjibbe

### Discussion/action points

Nr.	Description	Responsible
1.	<b>Al-MQW</b> Rene installed a new Al source in the reactor. Calibrations underway. QW design is underway in WP3.	Rene
2.	<b>Zn diffusion tests</b> Rene performed the diffusion tests on 3 wafers at 475, 500 and 525 °C, each temperature with different diffusion time. Results (CV) will be analyzed this week to obtain the diffusion rates for each epi. RTA and CV are done on old smart wafers with unsuccessful lasers, showing no difference in Zn concentration after RTA.	Rene
3.	<b>BCB planarization</b> Tjibbe got two wafers from Smart with polyimide for the planarization test. This will be done this week, followed by BCB etching tests on the same sample. The etching recipe has conflicts in the RIE with other recipes. Solution is under discussion with other users. Longfei suggested to try the standard recipe. Adhesion tests are still pending.	Tjibbe
4.	<b>Stepper process</b> Stepper is down again. Supporting engineer has been informed. Experiments pending.	Robert
5.	<b>Etching process</b> Smart optimized the present CH <sub>4</sub> -H <sub>2</sub> recipe and will reproduce it in the ICP in Nanolab. Oxford provided two baseline recipes for Cl <sub>2</sub> -CH <sub>4</sub> -H <sub>2</sub> with low etch rate (200 and 500 nm/min respectively). Longfei will start the tests with 4 wafers this week.	Rui Longfei
6.	<b>DUV</b> CDSEM test structures have been submitted in SP20.	Weiming
7.	<b>Planning and milestone list</b> Longfei updated the list of milestones with quantifiable criteria included. He will send it to each partner to check their responsible tasks. Comment from Rob: a more explicit plan for the short term (6 months) will be important, specifying each person's tasks and due dates. Comment from Kevin: the characterization techniques for each task should be thought through more carefully.	Longfei

Next meeting: 13:30-15:00, 1-5-2017, Flux 10.177